Special Issue

Simulation and Reliability Assessment of Advanced Packaging

Message from the Guest Editor

Simulation-based technology plays an important role in the design, structure optimization, and evaluation of the reliability life of advanced packaging, which has become a design trend in the electronics packaging community. The purpose of this Special Issue is to introduce the latest research results of simulation-based technology in advanced packaging today, and the topics to be covered include material characterization of electronic packaging, theoretical or empirical work, modeling, simulation technology, design and validation, AI-assisted design-on-simulation technology, and reliability life prediction. Prospective authors are encouraged to contribute their original and unpublished works in the abovementioned areas. It is my pleasure to invite you to submit a manuscript for this Special Issue. Full papers, letters, and reviews are all welcome.

Guest Editor

Prof. Dr. Kuo-Ning Chiang
Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu 300, Taiwan

Deadline for manuscript submissions

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Materials
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
materials@mdpi.com

mdpi.com/journal/materials

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Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Editor-in-Chief

Prof. Dr. Maryam Tabrizian
1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada
2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

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